

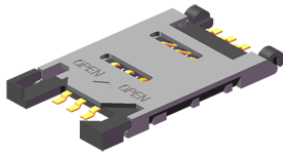
Operation: SMT & Hinge & 铰链式 全塑体 MINI SIM卡座



LTEM NO.: SIM-011B-R6 (Consumer Electronics)

(30.0L × 17.0W × 2.5H & MINI-SIM Sockets)

MEMORY-CARD-SOCKETS



Technical parameter

外焊贴装 SMT

側向導入 LATERAL

精密部品 NICETY

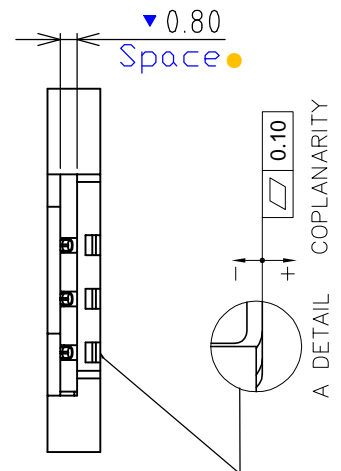
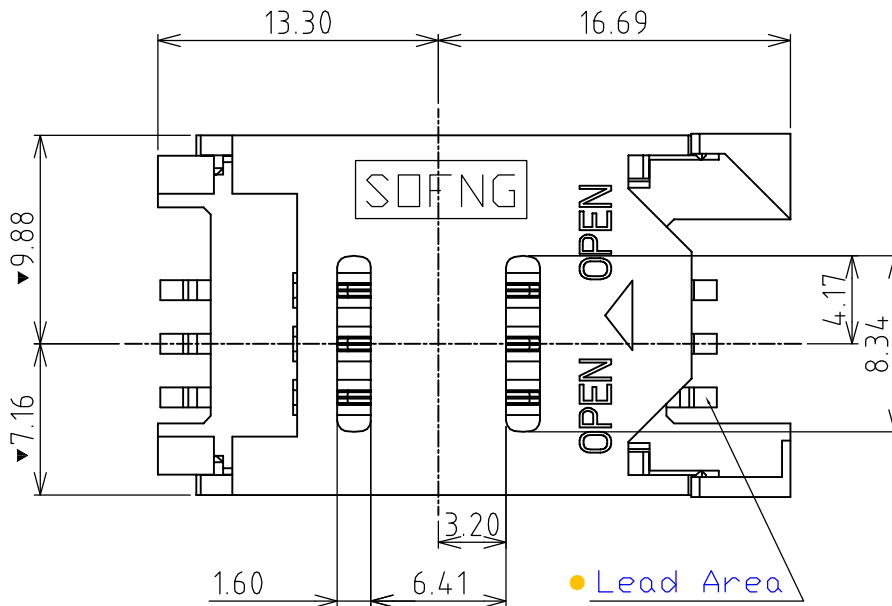
可靠 STABILIZE

適合環保 RoHS

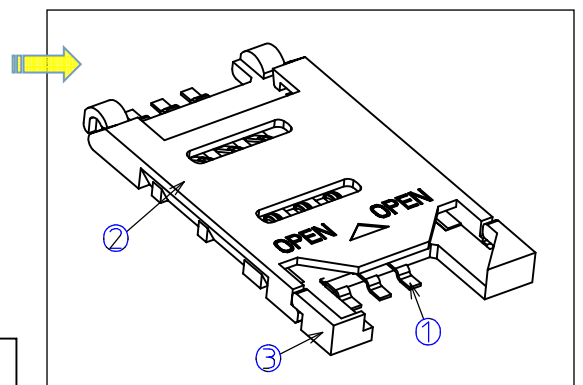
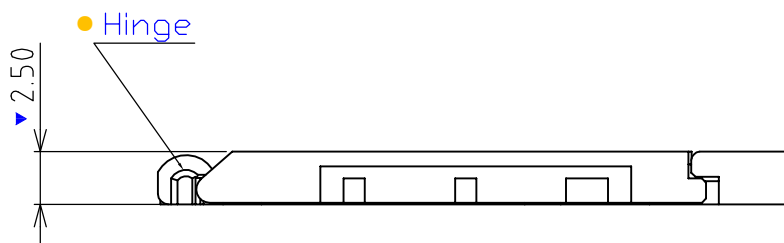
PROJECT	LEVEL	A[better product]		B[average product]	
Electrical Properties	Contact Rating	25mA, 24V DC			
	Initial Contact Resistance	30mΩ max.		50mΩ max.	
	Insulation Resistance	100MΩ min.500V DC			
	Withstand Voltage	500V AC for 1 minute		350 V AC for 1 minut	
Durable Performance	There No Load	5,000 Cycles		3,500 Cycles	
	Rated Load	3,500 Cycles		3,000 Cycles	
	Storage temp.	-25℃~+85℃(Operating Temp:)			

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Unit:mm



NAME	MATERIAL	
① CONTACT	C5191-H 磷青铜 COPPER ALLOY[Gold Flash-6PIN]	
② COVER	LCP MG350 THERMOPLASTIC,UL 94V-0,COLOR:BLACK	
③ HOUSING	LCP S475 THERMOPLASTIC,UL 94V-0,COLOR:BLACK	

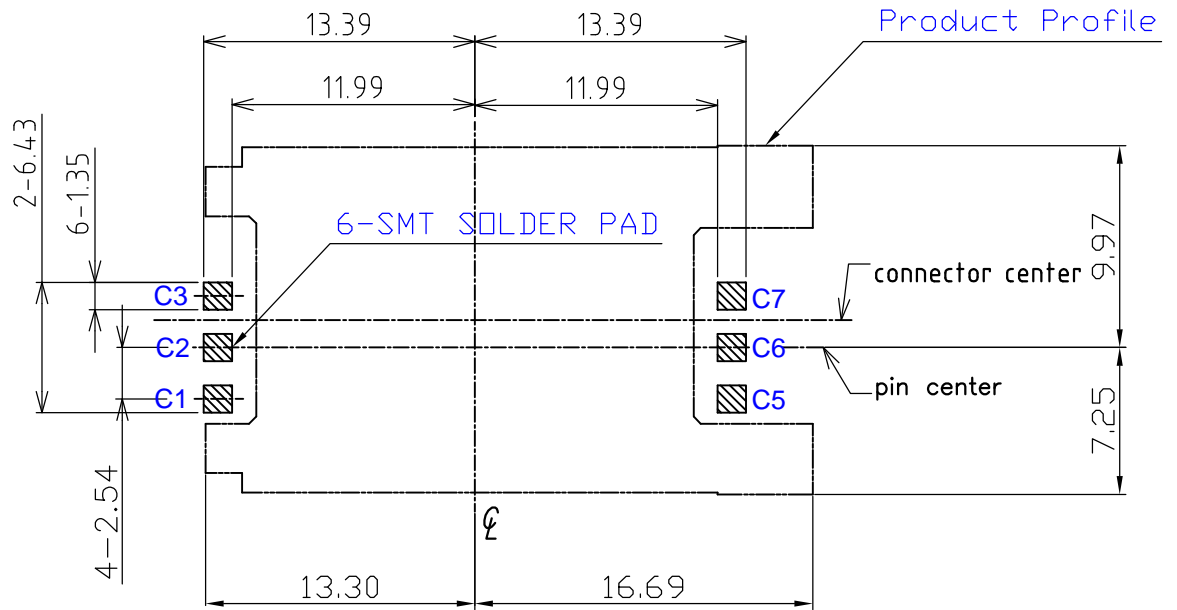


Operating Force

Inward 5.0~6.5N. (1N.=100gram-force)
 Exiting 5.0~6.5N. (1N.=100gram-force)

Solder-ability (Max.)

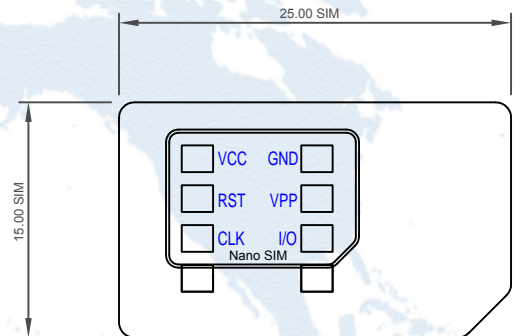
IR Reflow: 255°C, 5sec. Manual: 350°C, 3sec.



Pin definition

Pin No.	Pin NAME	Type	Description
C ①	卡電源	1	VCC
C ②	復位	1	RST
C ③	時鐘	1	CLK
C ⑤	接地	1	GND
C ⑥	Vpp	1	VPP
C ⑦	輸入/輸出	1	I/O

DECIMALS		ANGLES	
X	:±0.50	X°	:±3°
X.X	:±0.35	X.X°	:±1°
X.XX	:±0.25	X.XX°	:±0.5°

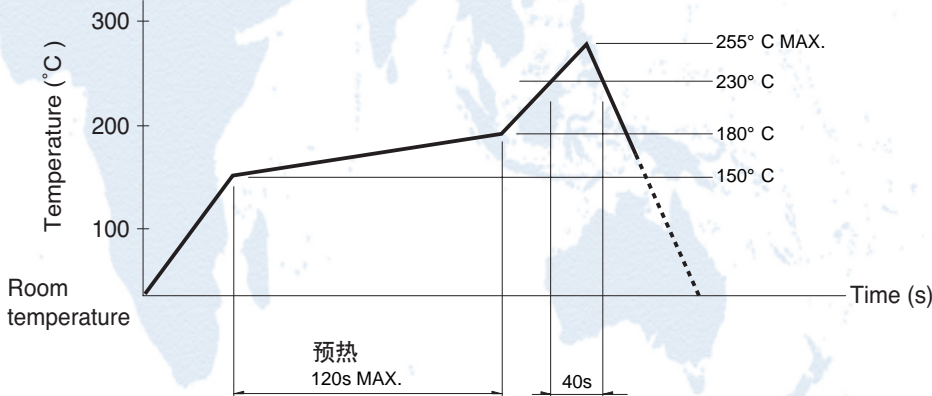


Reference

SIM CARD

回流方式的参考举例

1. 加热方式远红外线加热的上下加热方式。
2. 温度测量方式用 V0.1 ~ V0.2 的 CA(K) 或 CC(T) 进行测量。
3. 温度分布



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